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Mechanical design



SPECIFICATION FOR LCM+CTP Module

MODULE No:	ET043WV21-KT
CUSTOMER:	

YOURITECH	INITIAL	DATE
PREPARED BY		
CHECKED BY		
APPROVED BY		

CUSTOMER	INITIAL	DATE
APPROVED BY		



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1.Basic Specifications

* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silicon TFT as a switching device. This module is composed of a Transmissive type TFT-LCD Panel, driver circuit, capacitance touch panel, back-light unit. The resolution of a 4.3 " TFT-LCD contains 800x480 pixels, and can display up to 16.7M colors.

1.1 TFT Features

General Information Items	Specification	Unit	Note
	Main Panel		
Display area(AA)	95.04(H)*53.86(V) (4.3inch)	mm	
Driver element	TFT active matrix	-	
Display colors	65K/262K16.7M	colors	
Number of pixels	800(RGB)*480	dots	
Pixel arrangement	RGB vertical stripe	-	
Pixel pitch	0.1188(H)*0.1122(V)	mm	
Viewing angle	Free	o'clock	
Controller IC	ST7262	-	
Display mode	Transmissive /Normally Black	-	
LCM Interface	16/18/24BIT RGB	-	
Operating temperature	-30~+85	°C	
Storage temperature	-30~+85	°C	
Module bonding technology	Tape bonding between LCM and CTP	-	

1.2 CTP Features

General Information Items	Specification	Unit	Note
	Main Panel		
Resolution	800(H)*480(V)	-	
Structure	G+G	-	
Controller IC	FT5436DQQ	-	
Interface	I2C	-	
Slave Address	0x38(7bit)/8bit:0x70(Write) 0x71(Read)	-	
Touch mode	Five points and Gestures	-	-

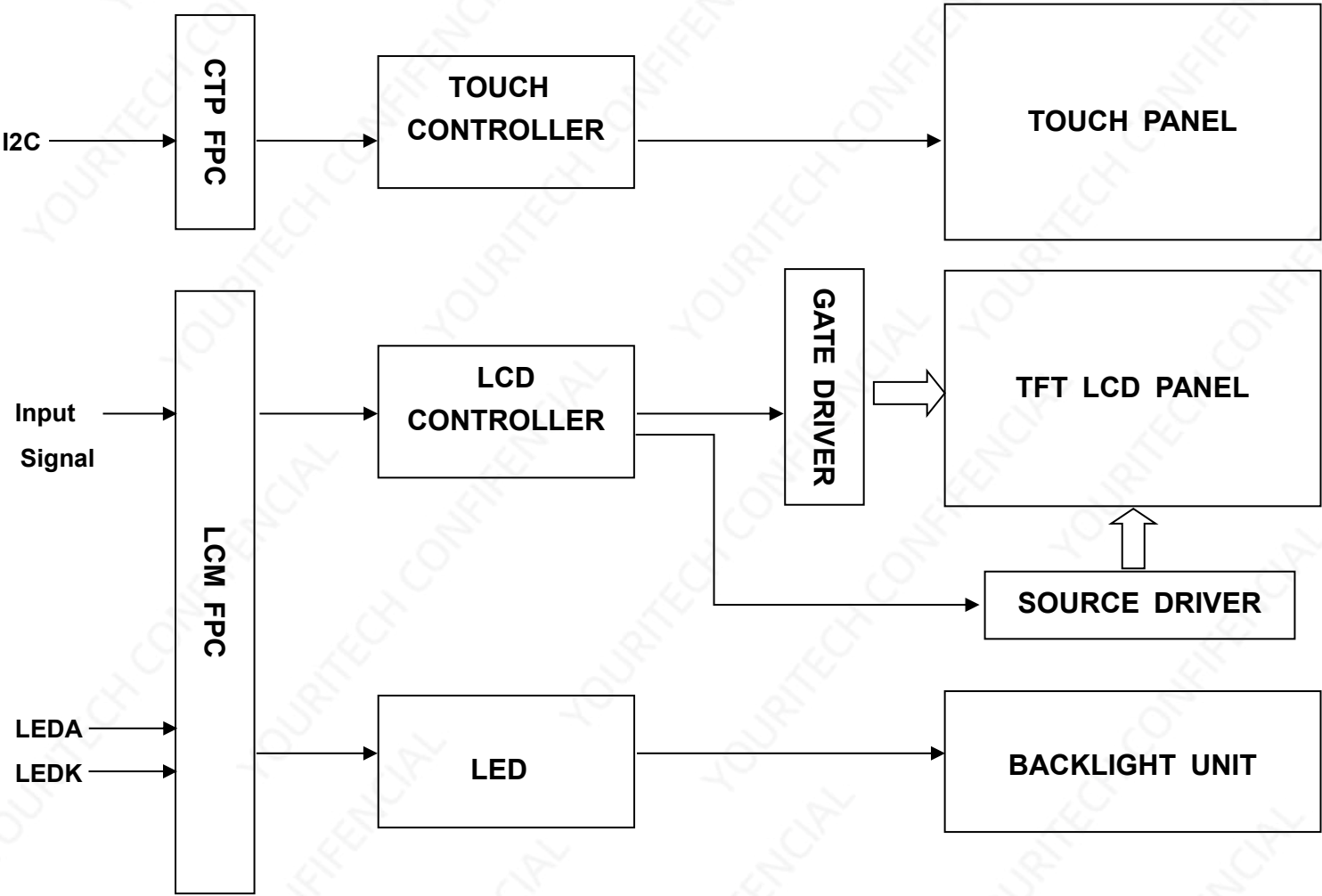


Logic level	3.3	V	
-------------	-----	---	--

1.3 Mechanical Information

Item		Min.	Typ.	Max.	Unit	Note
Module size	Horizontal(H)	-	105.40	-	mm	
	Vertical(V)	-	67.15	-	mm	
	Depth(D)	-	4.36	-	mm	
Weight		-	TBD	-	g	

2. Block Diagram





4. Input terminal Pin Assignment

4.1 TFT PIN Define

NO.	SYMBOL	DISCRIPTION	I/O
1	VLED-	Cathode pin OF backlight	P
2	VLED+	Anode pin of backlight	P
3	GND	Ground.	P
4	VDD	Supply voltage(3.3V).	P
5	R0	Red data input.	I
6	R1	Red data input.	I
7	R2	Red data input.	I
8	R3	Red data input.	I
9	R4	Red data input.	I
10	R5	Red data input.	I
11	R6	Red data input.	I
12	R7	Red data input.	I
13	G0	Green data input.	I
14	G1	Green data input.	I
15	G2	Green data input.	I
16	G3	Green data input.	I
17	G4	Green data input.	I
18	G5	Green data input.	I
19	G6	Green data input.	I
20	G7	Green data input.	I
21	B0	Blue data input.	I
22	B1	Blue data input.	I
23	B2	Blue data input.	I



24	B3	Blue data input.	I
25	B4	Blue data input.	I
26	B5	Blue data input.	I
27	B6	Blue data input.	I
28	B7	Blue data input.	I
29	GND	Ground.	P
30	PCLK	Clock signal. Latching data at the rising edge	I
31	DISP	Standby setting for testing, it should be connected to VDDIO in normal operation mode. If connected to GND, the IC is in standby mode.	I
32	HSYNC	Horizontal Sync input. Negative polarity.	I
33	VSNC	Vertical Sync input. Negative polarity.	I
34	DE	Data input Enable. Active High to enable the data input Bus under "DE Mode".	I
35	NC	--	--
36	GND	Ground.	P
37	XR(NC)	Touch panel Right Glass Terminal	A/D
38	YD(NC)	Touch panel Bottom Film Terminal	A/D
39	XL(NC)	Touch panel LIFT Glass Terminal	A/D
40	YU(NC)	Touch panel Top Film Terminal	A/D



4.2 CTP PIN Define

NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	P
2	VDD	Supply voltage.	P
3	SCL	I2C clock input.	P
4	NC	NC	--
5	SDA	I2C data input and output	I/O
6	NC	NC	--
7	RST	External Reset, Low is active.	I
8	NC	NC	--
9	INT	External interrupt to the host.	I
10	GND	Ground.	P



5. LCD Optical Characteristics

5.1 Optical specification

Item		Symbol	Condition	Min.	Typ.	Max.	Unit.	Note
Contrast Ratio		CR	$\Theta=0$ Normal viewing angle	--	1200	--		(1)(2)
Response time	Rising	T_R+T_F		--	30	40	msec	(1)(3)
	Falling			--				
Color Gamut		S(%)		--	50	--	%	
Color Filter Chromaticity	White	W_X		0.2600	0.3000	0.3400	CF glass	(1)(4)
		W_Y		0.2915	0.3315	0.3715		
	Red	R_X		0.5709	0.5909	0.6109		
		R_Y		0.3394	0.3594	0.3794		
	Green	G_X		0.3132	0.3332	0.3532		
		G_Y		0.5469	0.5669	0.5869		
	Blue	B_X		0.1355	0.1555	0.1755		
		B_Y		0.0946	0.1146	0.1346		
Viewing angle	Hor.	Θ_L	CR>10	--	80	--		(1)(4)
		Θ_R		--	80	--		
	Ver.	Θ_U		--	80	--		
		Θ_D		--	80	--		
Option View Direction		Free						

*The data comes from the LCD specification.

Measuring Condition

Measuring surrounding : dark room

Ambient temperature : $25\pm 2^\circ\text{C}$

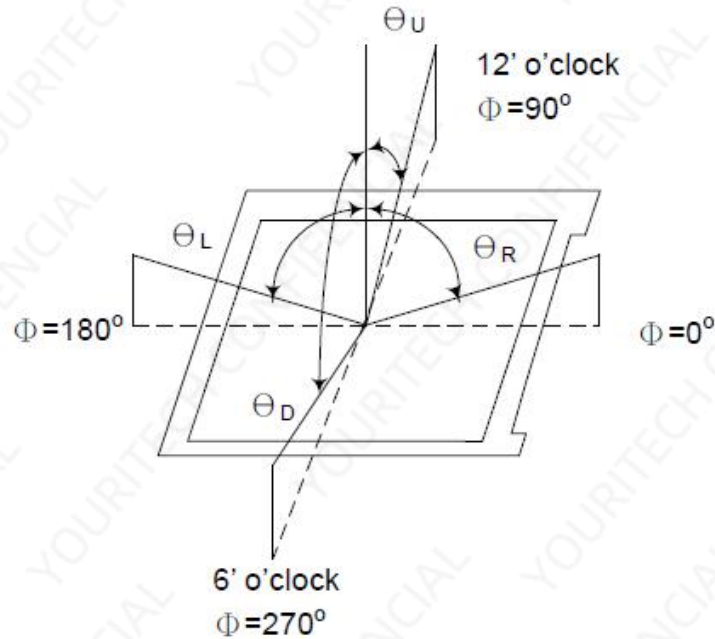
15min. warm-up time.

Measuring Equipment

FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.



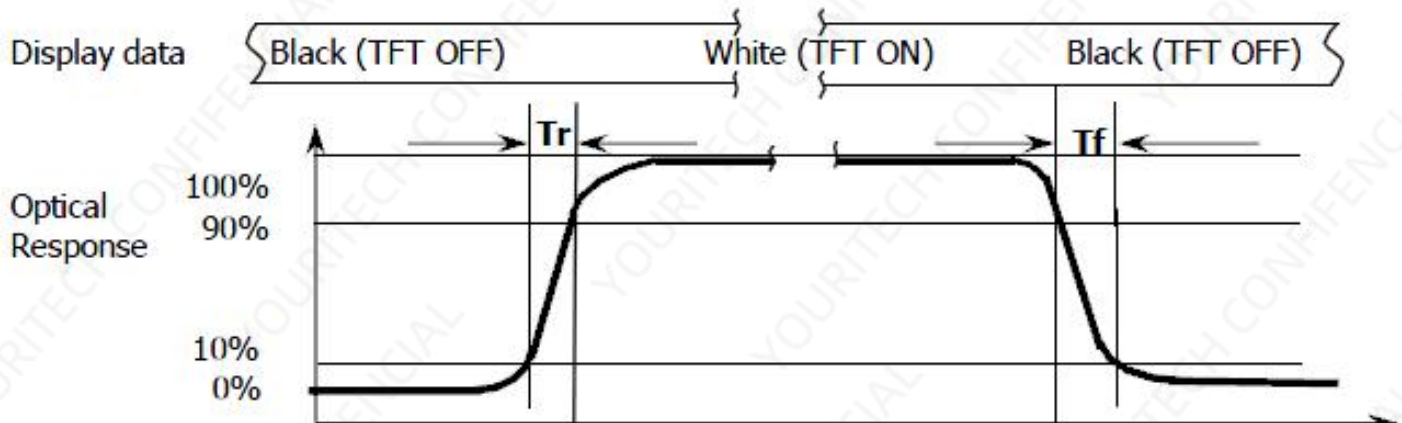
Note (1): Definition of Viewing Angle :



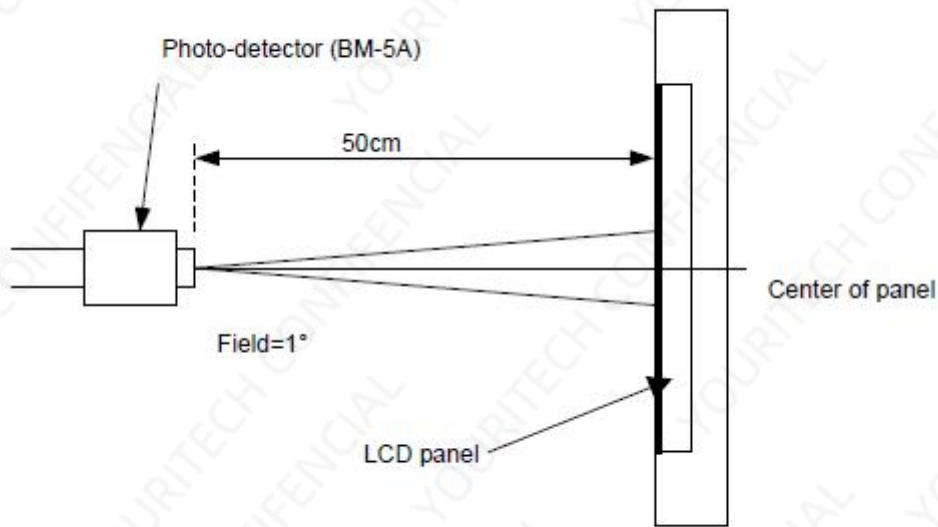
Note (2): Definition of Contrast Ratio(CR) :measured at the center point of panel

$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

Note (3): Response Time



Note (4): Definition of optical measurement setup



6. Electrical Characteristics

6.1 Absolute Maximum Rating

Characteristics	Symbol	Min.	Max.	Unit	Note
Digital Supply Voltage	VDD	-0.3	4.0	V	Note1
Operating temperature	T _{OP}	-30	+85	°C	
Storage temperature	T _{ST}	-30	+85	°C	

NOTE1: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

6.2 DC Electrical Characteristics

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Note
Digital Supply Voltage	VDD	3.0	3.3	3.6	V	
Normal mode Current	IDD	--	40	--	mA	
Level input voltage	V _{IH}	0.7VDD		VDD	V	
	V _{IL}	GND		0.3 VDD	V	
Level output voltage	V _{OH}	VDD-0.4		--	V	
	V _{OL}	GND		GND+0.4	V	



6.3 LED Backlight Characteristics

The back-light system is edge-lighting type with 24 chips LED

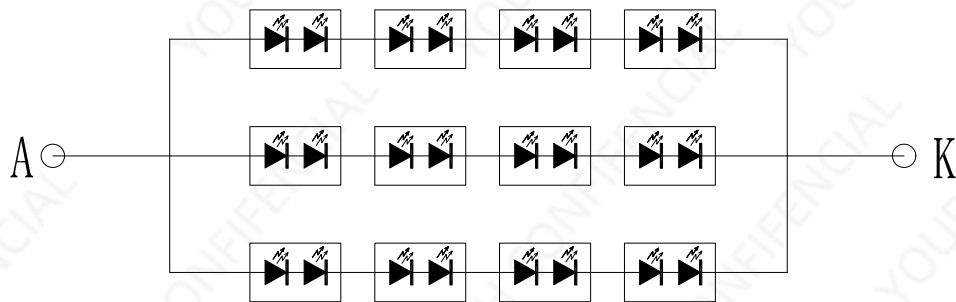
Item	Symbol	Min.	Typ.	Max.	Unit	Note
Forward Current	I_F	55	60	--	mA	
Forward Voltage	V_F	--	25.6	--	V	
LCM Luminance	LV	1077	1137	--	cd/m2	Note3
LED life time	Hr	--	50000	--	Hour	Note1,2
Uniformity	Avg	80	--	--	%	Note3

Note1: LED life time (Hr) can be defined as the time in which it continues to operate under the condition:

$T_a = 25 \pm 3^\circ \text{C}$, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note 2: The "LED life time" is defined as the module brightness decrease to 50% original brightness at

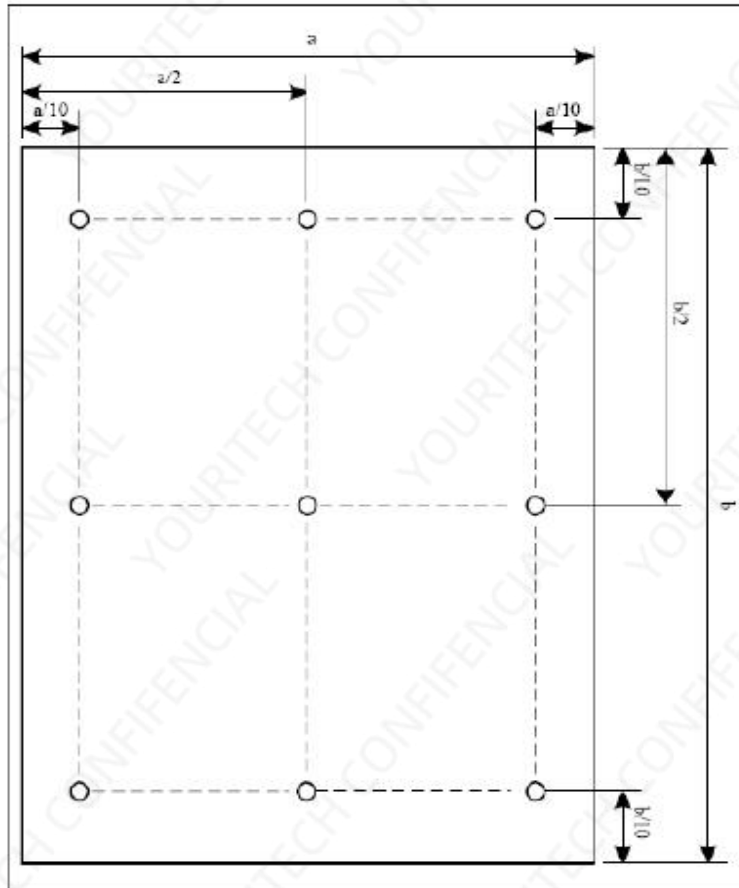
$T_a = 25^\circ \text{C}$ and $I_L = 60 \text{mA}$. The LED lifetime could be decreased if operating I_L is larger than 60mA. The constant current driving method is suggested.



B/L Circuit



Note (3) Luminance Uniformity of these 9 points is defined as below:



$$\text{Uniformity} = \frac{\text{minimum luminance in 9 points (1-9)}}{\text{maximum luminance in 9 points (1-9)}}$$

$$\text{Luminance} = \frac{\text{Total Luminance of 9 points}}{9}$$

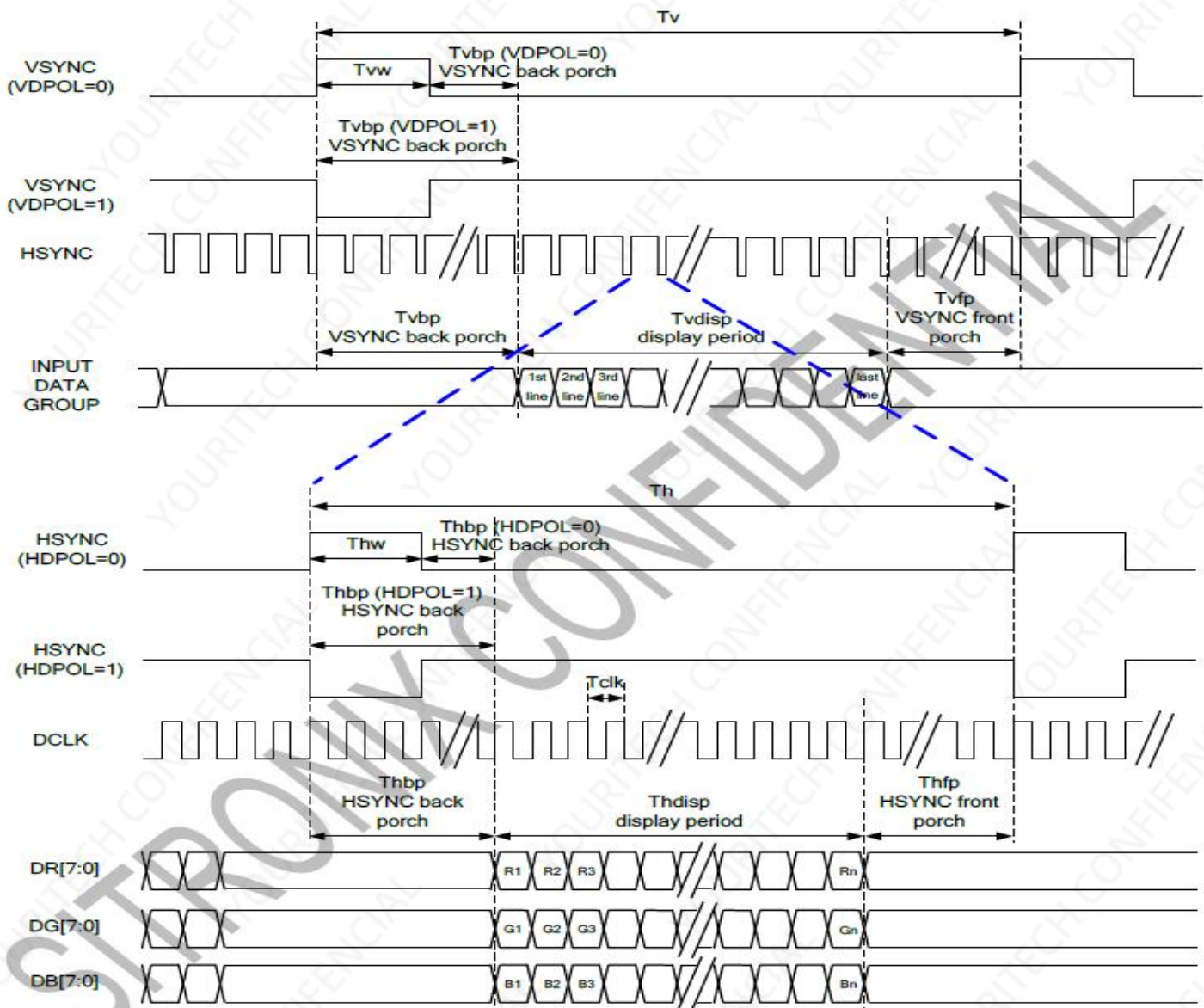


7. RGB Interface Characteristics

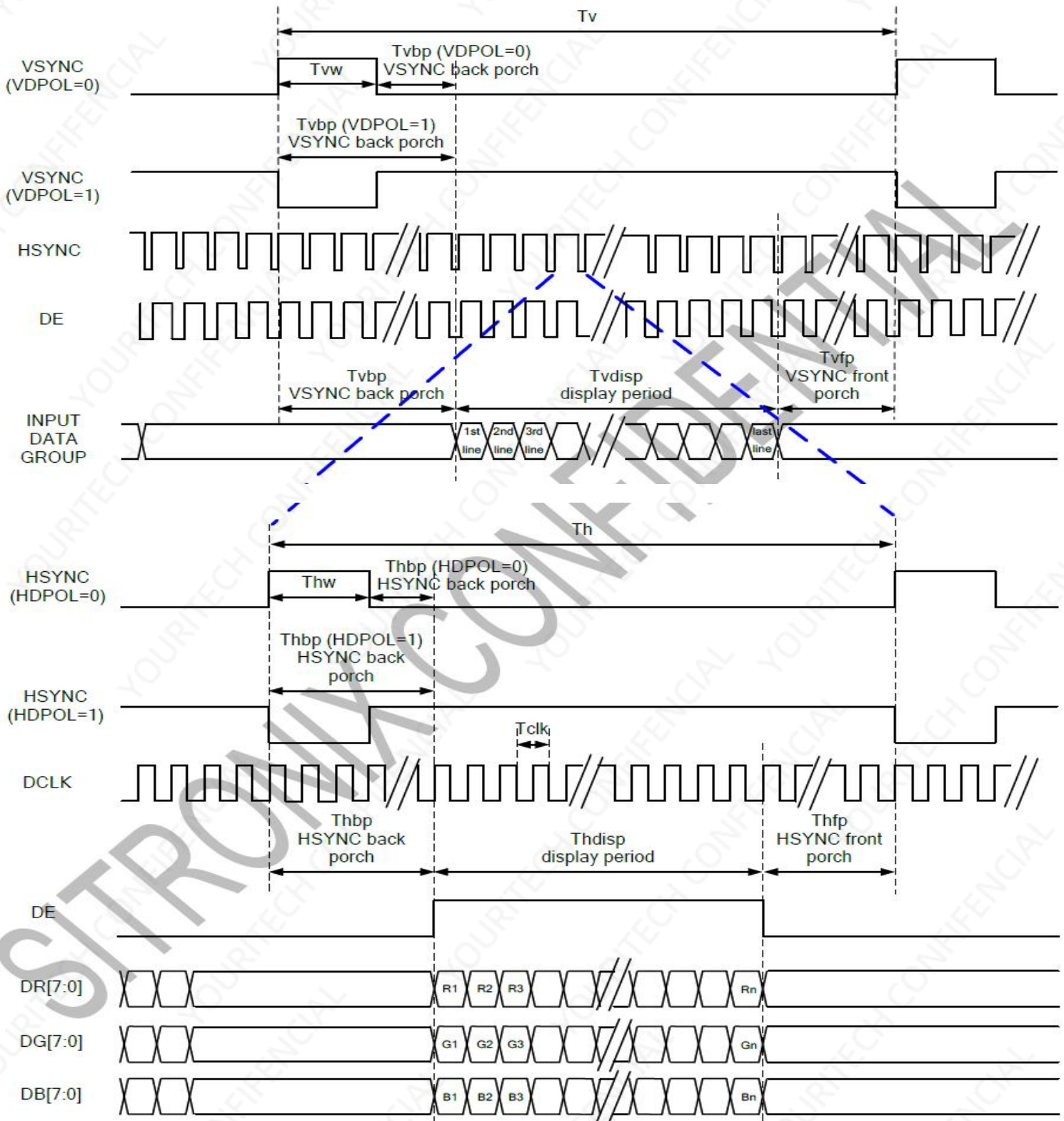
RGB Mode Selection Table	DCLK	HSYNC	VSYNC	DE
SYNC - DE Mode	Input	Input	Input	Input
SYNC Mode	Input	Input	Input	GND
DE Mode	Input	GND	GND	Input

Note: "Input" means these signals are driven by host side

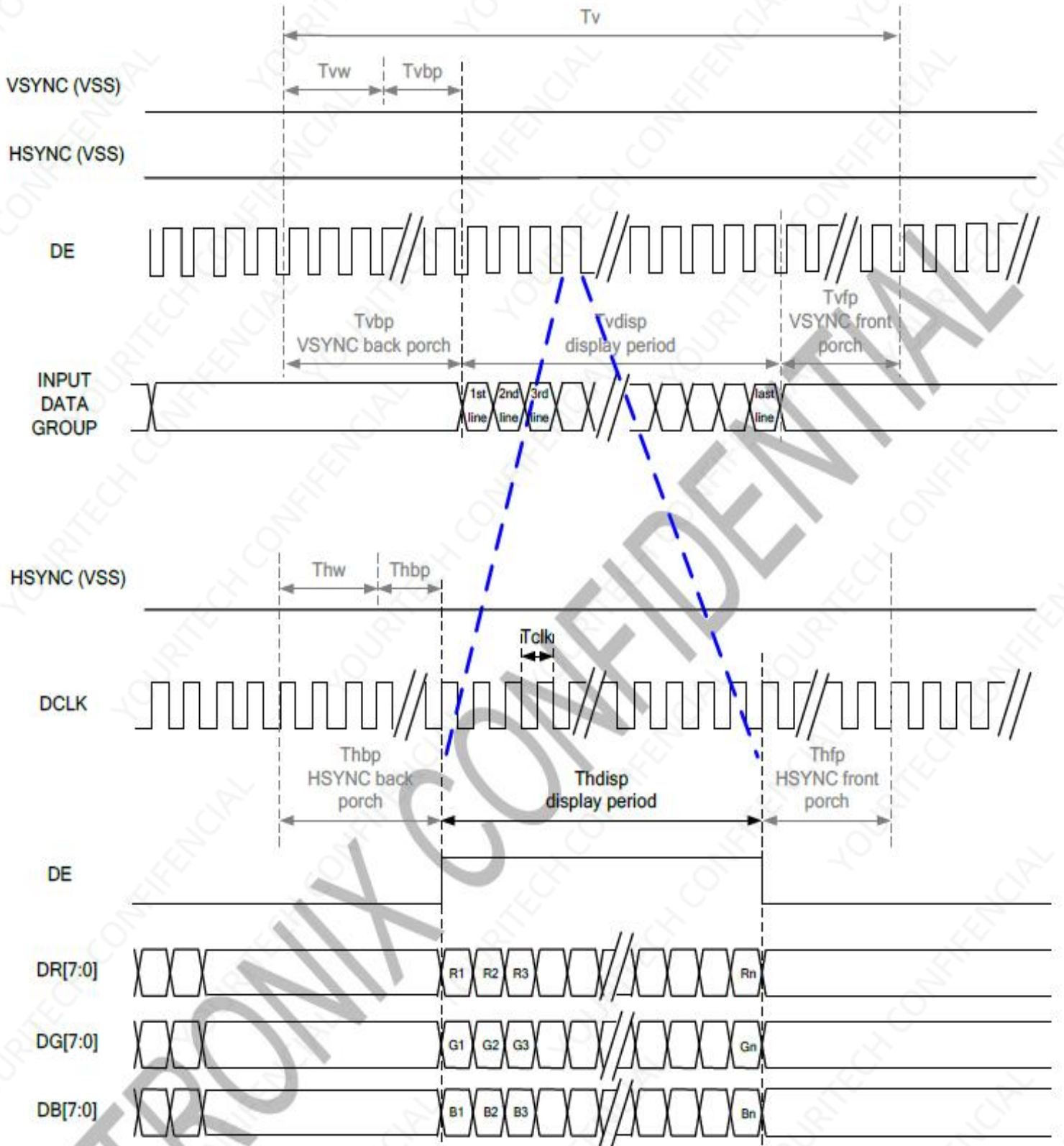
7.1 SYNC Mode



7.2 SYNC-DE Mode



7.3 DE Mode



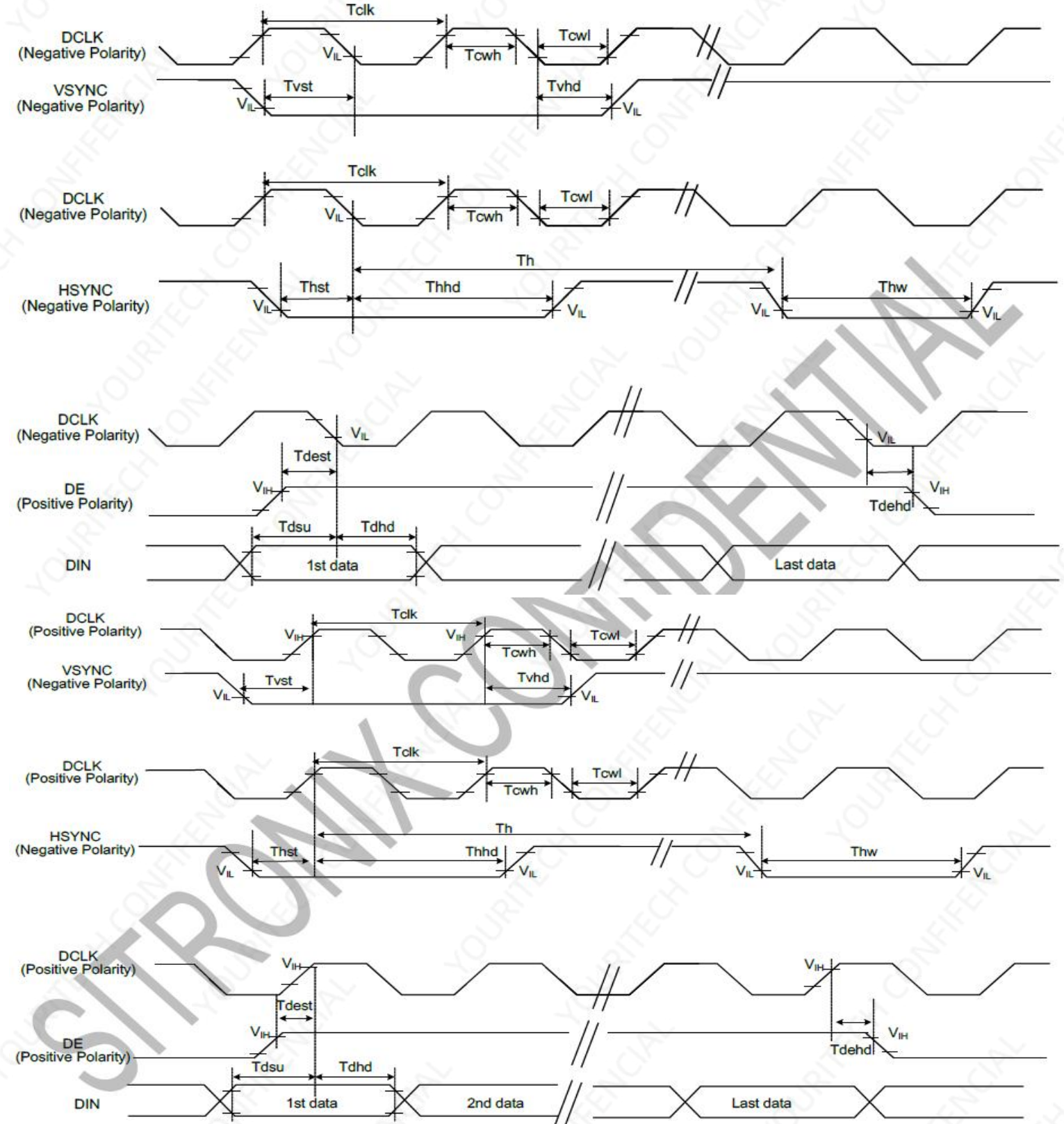
Parallel 24-bit RGB Input Timing (PVDD=PVDD1=VDD=VDDI= 3.3V, AGND= 0V, TA=25°C)

Parallel 24-bit RGB Interface Timing Table							
Item		Symbol	Min.	Typ.	Max.	Unit	Remark
DCLK Frequency		Fclk	23	25	27	MHz	
HSYNC	Period Time	Th	808	816	896	DCLK	
	Display Period	Thdisp	800			DCLK	
	Back Porch	Thbp	4	8	48	DCLK	
	Front Porch	Thfp	4	8	48	DCLK	
	Pulse Width	Thw	2	4	8	DCLK	
VSYNC	Period Time	Tv	488	496	504	HSYNC	
	Display Period	Tvdisp	480			HSYNC	
	Back Porch	Tvbp	4	8	12	HSYNC	
	Front Porch	Tvfp	4	8	12	HSYNC	
	Pulse Width	Tvw	2	4	8	HSYNC	



8. AC Electrical Characteristics

8.1 System Bus Timing for RGB Interface

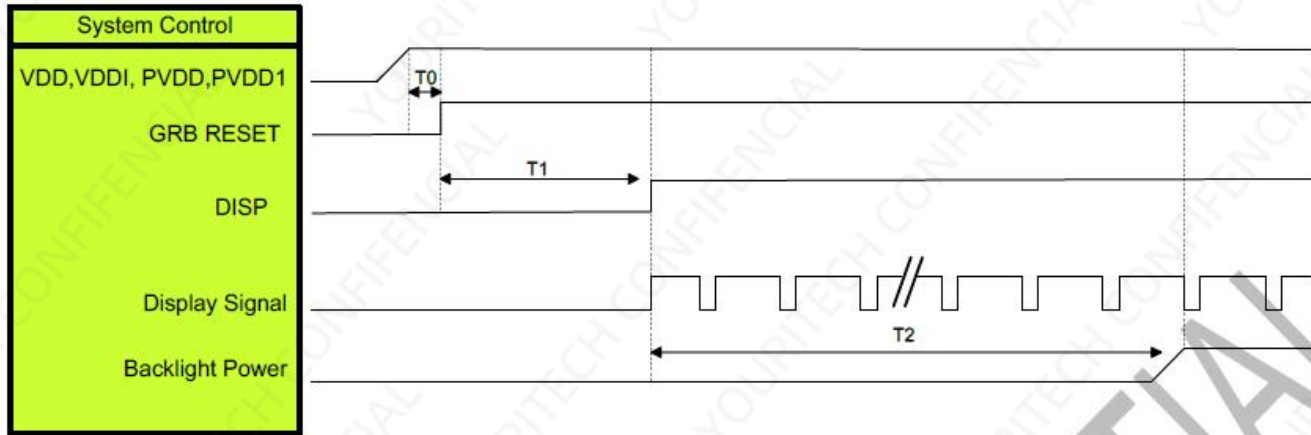


Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
CLK Pulse Duty	Tcw	40	50	60	%	
HSYNC Width	Thw	2	-	-	DCLK	
HSYNC Period	Th	55	60	65	us	
VSYNC Setup Time	Tvst	12	-	-	ns	
VSYNC Hold Time	Tvhd	12	-	-	ns	
HSYNC Setup Time	Thst	12	-	-	ns	
HSYNC Hold Time	Thhd	12	-	-	ns	
Data Setup Time	Tdsu	12	-	-	ns	
Data Hold Time	Tdhd	12	-	-	ns	
DE Setup Time	Tdest	12	-	-	ns	
DE Hold Time	Tdehd	12	-	-	ns	



9. POWER ON/OFF SEQUENCE

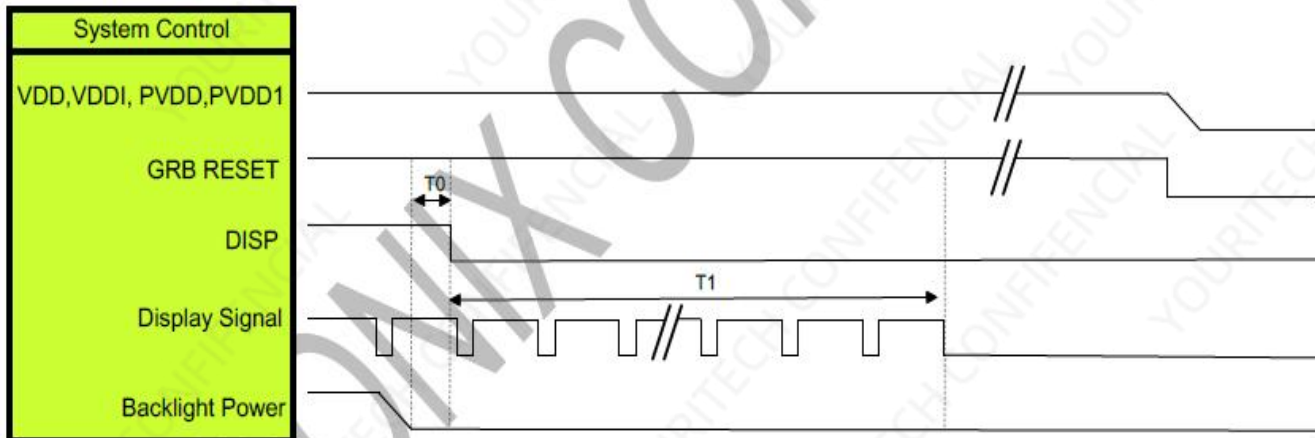
9.1 Power On Sequence



Symbol	Description	Min. Time	Unit
T0	System power stability to GRB RESET signal	0	ms
T1	GRB RESET= "High" to DISP="High"	10	ms
T2	Display Signal output to Backlight Power on	250	ms

Note: RGB interface Display signal: DCLK; VSYNC; HSYNC; DE; DR[7:0]; DG[7:0]; DB[7:0]

9.2 Power Off Sequence



Symbol	Description	Min. Time	Unit
T0	Backlight Power off to DISP="Low"	5	ms
T1	DISP="Low" to IC internal voltage discharge complete	100	ms

Note: RGB interface Display signal: DCLK; VSYNC; HSYNC; DE; DR[7:0]; DG[7:0]; DB[7:0]



10. CTP Specification

10.1 Electrical Characteristics

10.1.1 Absolute Maximum Rating

Item	Symbol	Min.	Max.	Unit	Note
Power Supply Voltage	VDD	2.7	3.6	V	
Operating temperature	T _{OP}	-30	+85	°C	
Storage temperature	T _{ST}	-30	+85	°C	

10.1.2 DC Electrical Characteristics (Ta=25°C)

Item	Min.	Typ.	Max.	Unit	Note
Power Supply Voltage/VDD	2.7	3.3	3.47	V	
Normal mode operating current	--	11	--	mA	
Sleep mode operating current	--	42	--	uA	
Monitor mode operating current	--	0.43	--	mA	
Digital Input low voltage/VIL	-0.3	--	0.3*VDD	V	
Digital Input high voltage/VIH	0.7*VDD	--	VDD	V	
Digital Output low voltage/VOL	--	--	0.3*VDD	V	
Digital Output high voltage/VOH	0.7*VDD	--	--	V	



10.1.3 AC Characteristics

AC Characteristics of Oscillators

Item	Symbol	Unit	Test Condition	Min.	Typ.	Max.	Note
OSC clock 1	fosc1	MHz	VDD3 = 2.8V; Ta=25°C	49	50	51	

10.2 POWER ON/Reset Sequence

Reset should be pulled down to be low before powering on and powering down. I2C shouldn't be used by other devices during Reset time after VDD powering on (Trtp). INT signal will be sent to the host after initial-izing all parameters and then start to report points to the host. If Power is down, the voltage of supply must be below 0.3V and Tpdtr is more than 1ms.

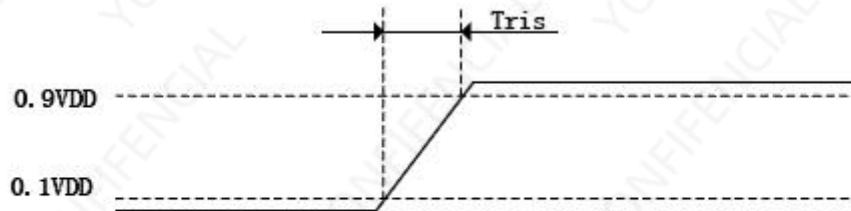


Figure 3-3 Power on time

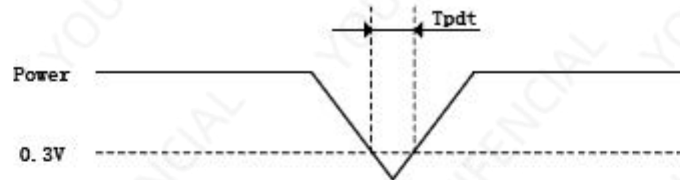


Figure 3-4 Power Cycle requirement

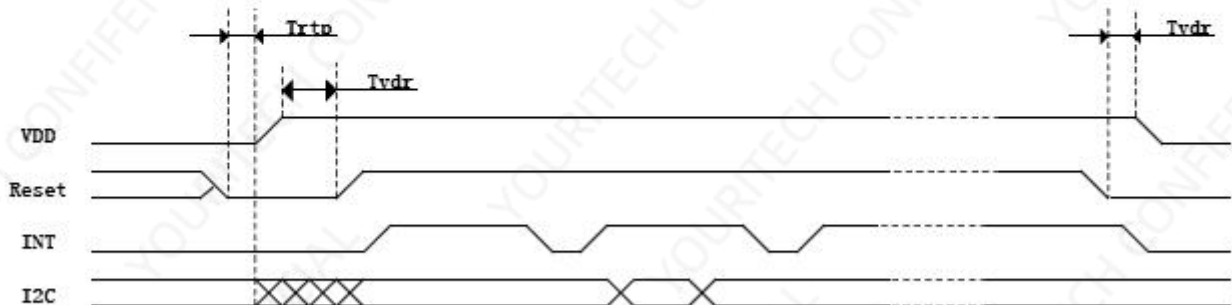


Figure 3-5 Power on Sequence



Reset time must be enough to guarantee reliable reset, the time of starting to report point after resetting approach to the time of starting to report point after powering on.

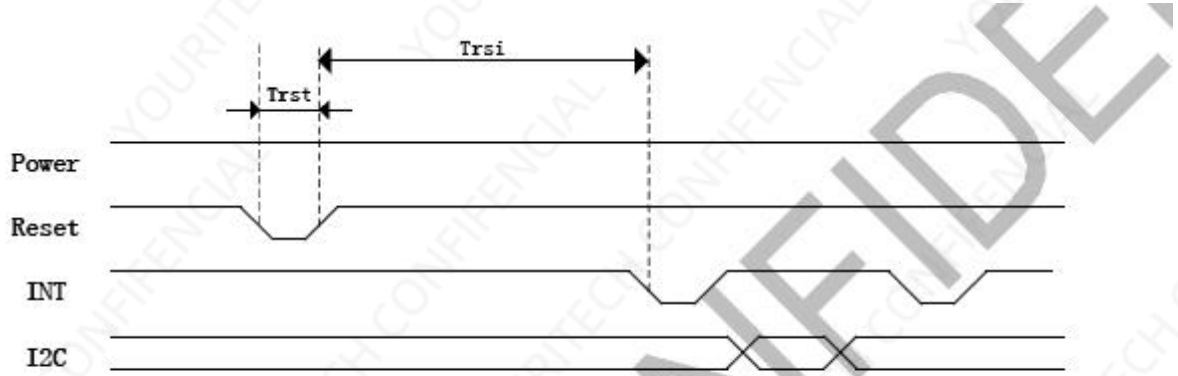


Figure 3-6 Reset Sequence

Table 3-5 Power on/Reset Sequence Parameters

Parameter	Description	Min	Max	Units
Tris	Rise time from 0.1VDD to 0.9VDD	—	5	ms
Tpdt	Time of the voltage of supply being below 0.3V	5	—	ms
Trtp	Time of resetting to be low before powering on	100	—	μs
Tvdr	Reset time after VDD powering on	1	—	ms
Trsi	Time of starting to report point after resetting	—	200	ms
Trst	Reset time	1	—	ms



10.3 I2C Timing

FT5436 supports the I2C interfaces, which can be used by a host processor or other devices.

The I2C is always configured in the Slave mode. The data transfer format is shown in **Figure 2-4**.

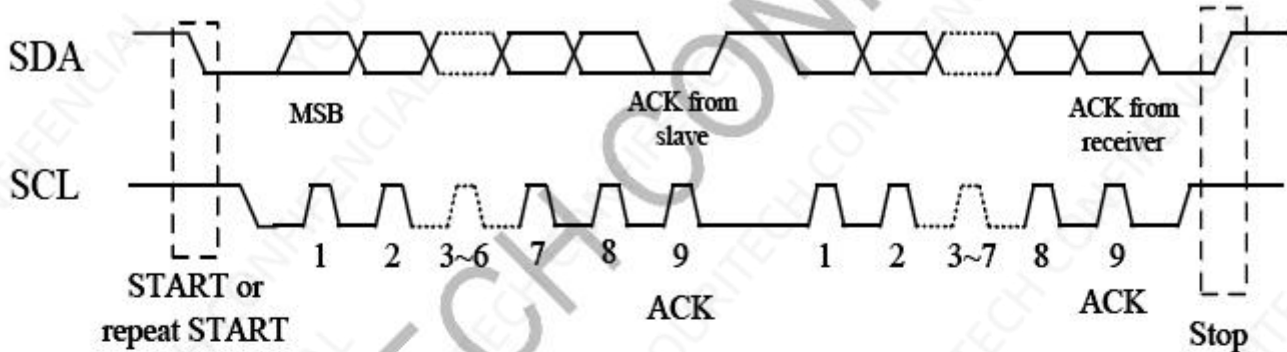


Figure 2-4 I2C Serial Data Transfer Format

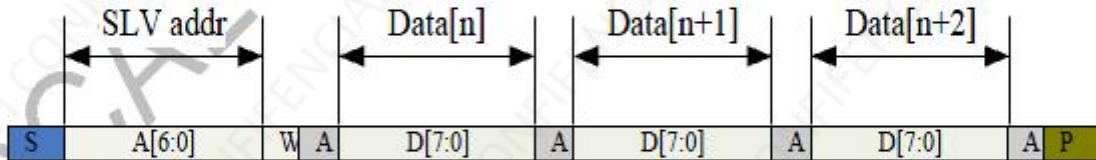


Figure 2-5 I2C master write, slave read

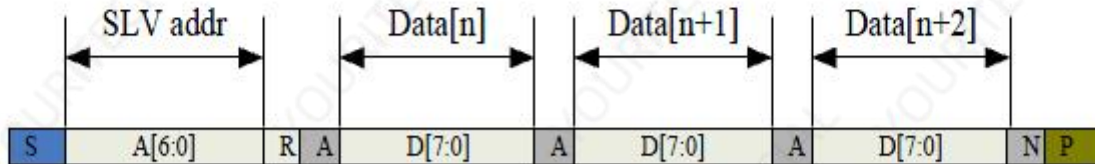


Figure 2-6 I2C master read, slave write

Table 2-1 lists the meanings of the mnemonics used in the above figures.

Table 2-1 Mnemonics Description



Mnemonics	Description
S	I2C Start or I2C Restart
A[6:0]	Slave address
R/ W	READ/WRITE bit, '1' for read, '0' for write
A(N)	ACK(NACK) bit
P	STOP: the indication of the end of a packet (if this bit is missing, S will indicate the end of the current packet and the beginning of the next packet)

I2C Interface Timing Characteristics is shown in Table 2-2.

Table 2-2 I2C Timing Characteristics

Parameter	Min	Max	Unit
SCL frequency	0	400	KHz
Bus free time between a STOP and START condition	1.3		us
Hold time (repeated) START condition	0.6		us
Data setup time	100		ns
Setup time for a repeated START condition	0.6		us
Setup Time for STOP condition	0.6		us



11. LCD Module Out-Going Quality Level

11.1 VISUAL & FUNCTION INSPECTION STANDARD

11.1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

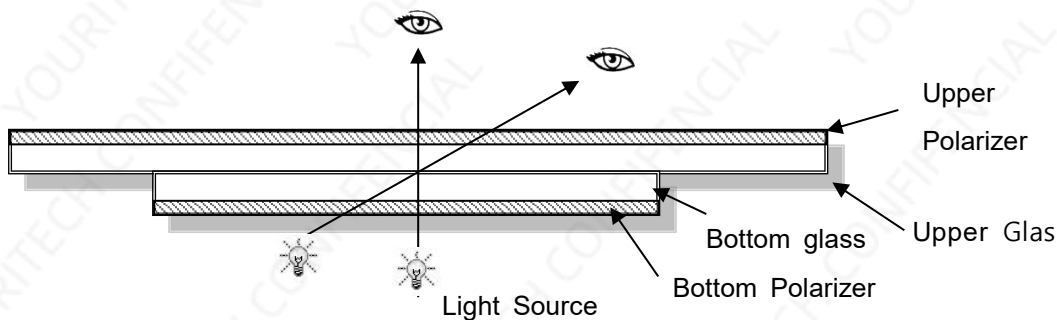
Temperature : $25\pm 5^{\circ}\text{C}$

Humidity : $65\%\pm 10\%\text{RH}$

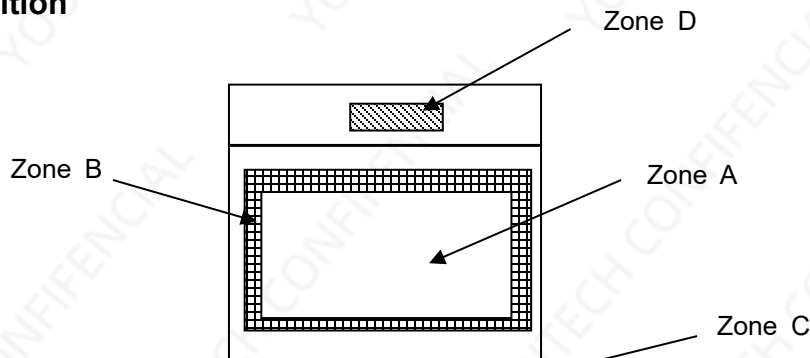
Viewing Angle : Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance:30-50cm



11.1.2 Definition



Zone A : Effective Viewing Area(Character or Digit can be seen)

Zone B : Viewing Area except Zone A

Zone C : Outside (Zone A+Zone B) which can not be seen after assembly by customer .)

Zone D : IC Bonding Area

Note:

As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer



11.1.3 Sampling Plan

According to GB/T 2828.1-2012 ; , normal inspection, Class II

AQL:

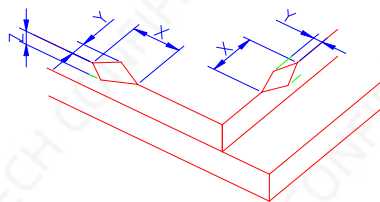
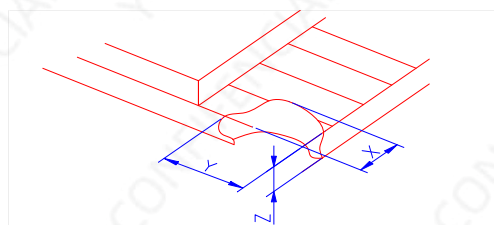
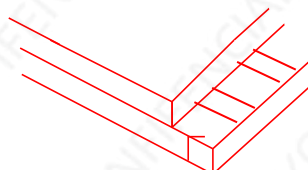
Major defect	Minor defect
0.65	1.5

LCD: Liquid Crystal Display , TP: Touch Panel , LCM: Liquid Crystal Module

No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	1) No display, Open or miss line 2) Display abnormally, Short 3) Backlight no lighting, abnormal lighting. 4) TP no function	Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	
4	Color tone	Color unevenness, refer to limited sample	Minor
5	Spot Line defect	Light dot, Dim spot, Polarizer Bubble ; Polarizer accidented spot.	
6	Soldering appearance	Good soldering , Peeling off is not allowed.	
7	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	



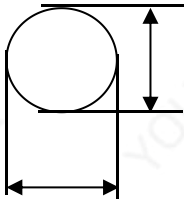
11.1.4 Criteria (Visual)

Number	Items	Criteria(mm)						
1.0 LCD Crack/Broken NOTE: X: Length Y: Width Z: Height L: Length of IT O, T: Height of LCD	(1) The edge of LCD broken	 <table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>≤3.0mm</td><td><Inner border line of the seal</td><td>≤T</td></tr></table>	X	Y	Z	≤3.0mm	<Inner border line of the seal	≤T
	X	Y	Z					
	≤3.0mm	<Inner border line of the seal	≤T					
(2)LCD corner broken	 <table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>≤3.0mm</td><td>≤L</td><td>≤T</td></tr></table>	X	Y	Z	≤3.0mm	≤L	≤T	
X	Y	Z						
≤3.0mm	≤L	≤T						
(3) LCD crack	 Crack Not allowed							



2.0

Spot defect



X

Y

$\Phi=(X+Y)/2$

① light dot (LCD/TP/Polarizer black/white spot , light dot, pinhole, dent, stain)

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi\leq0.10$	Ignore		Ignore
$0.10<\Phi\leq0.25$	3(distance $\geq 10\text{mm}$)		
$0.25<\Phi\leq0.3$	2		
$\Phi>0.35$	0		

②Dim spot (LCD/TP/Polarizer dim dot, light leakage, dark spot)

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi\leq0.1$	Ignore		Ignore
$0.10<\Phi\leq0.25$	3(distance $\geq 10\text{mm}$)		
$0.25<\Phi\leq0.3$	2		
$\Phi>0.35$	0		

③ Polarizer accidented spot

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi\leq0.2$	Ignore		Ignore
$0.3<\Phi\leq0.5$	2(distance $\geq 10\text{mm}$)		
$\Phi>0.5$	0		

④Pixel bad points (light dot, Dim dot, color dot)

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi\leq0.1$	Ignore		Ignore
$0.15<\Phi\leq0.25$	2(distance $\geq 10\text{mm}$)		
$\Phi>0.3$	0		

⑤ Polarizer Bubble

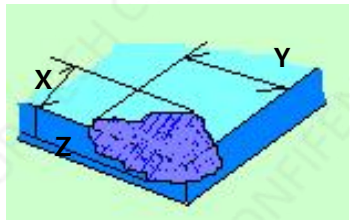
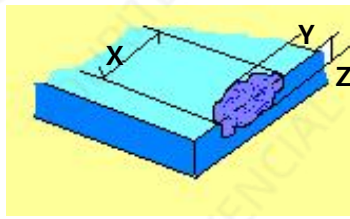
Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi\leq0.2$	Ignore		Ignore
$0.3<\Phi\leq0.4$	3(distance $\geq 10\text{mm}$)		
$0.5<\Phi\leq0.6$	2		



3.0	Line defect (LCD/TP /Polarizer backlight black/white line, scratch, stain)	Width(mm)	Length(m m)	Acceptable Qty		
				A	B	C
		$\Phi \leq 0.05$	Ignore	Ignore		Ignore
		$0.05 < W \leq 0.06$	$L \leq 4.0$	$N \leq 3$		
		$0.07 < W \leq 0.08$	$L \leq 3.0$	$N \leq 2$		
$0.08 < W$	Define as spot defect					
4.0	Electronic Components SMT	Not allow missing parts, solderless connection, cold solder joint, mismatch, The positive and negative polarity opposite				
5.0	Display color& Brightness	1. Color: Measuring the color coordinates, The measurement standard according to the datasheet or samples. 2. Brightness: Measuring the brightness of White screen, The measurement standard according to the datasheet or Samples.				
6.0	LCD Mura	By 5% ND filter invisible.				

7.0	CTP Related	CTP Cover sensor acc identified black/white spot	Size Φ (mm)	Acceptable Qty			
				A	B	C	
			$\Phi \leq 0.1$	Ignore		Ignore	
			$0.1 < \Phi \leq 0.2$	3 (distance $\geq 10\text{mm}$)			
			$0.20 < \Phi \leq 0.25$	2			
			$\Phi > 0.3$	0			
		CTP Cover scratch	Width(mm)	Ignore (mm)	Acceptable Qty		
					A	B	C
			$\Phi \leq 0.05$	Ignore	Ignore		
			$0.05 < W \leq 0.06$	$L \leq 4.0$	$N \leq 3$		
			$0.07 < W \leq 0.08$	$L \leq 3.0$	$N \leq 2$		
			$0.08 < W$	Define as spot defect			



		<table><tr><td rowspan="5"> CTP Cover Pinhole/ Lack of ink </td><td> Zone Size (mm) </td><td colspan="2">Acceptable Qty</td></tr><tr><td>$\Phi \leq 0.1$</td><td colspan="2">C</td></tr><tr><td>$0.1 < \Phi \leq 0.2$</td><td colspan="2">Ignore</td></tr><tr><td>$0.25 < \Phi \leq 0.3$</td><td colspan="2">3(distance $\geq 10\text{mm}$)</td></tr><tr><td>$\Phi > 0.35$</td><td colspan="2">2</td></tr><tr><td></td><td></td><td colspan="2">0</td></tr></table>	CTP Cover Pinhole/ Lack of ink	Zone Size (mm)	Acceptable Qty		$\Phi \leq 0.1$	C		$0.1 < \Phi \leq 0.2$	Ignore		$0.25 < \Phi \leq 0.3$	3(distance $\geq 10\text{mm}$)		$\Phi > 0.35$	2				0	
CTP Cover Pinhole/ Lack of ink	Zone Size (mm)	Acceptable Qty																				
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	$\Phi > 0.35$	2																				
		0																				
	<table><tr><td rowspan="6"> CTP Bondi ng bubble/ accidented spot </td><td> Size $\Phi(\text{mm})$ </td><td colspan="2">Acceptable Qty</td></tr><tr><td></td><td>A</td><td>B</td></tr><tr><td>$\Phi \leq 0.1$</td><td colspan="2">Ignore</td></tr><tr><td>$0.15 < \Phi \leq 0.2$</td><td colspan="2">3(distance $\geq 10\text{mm}$)</td></tr><tr><td>$0.2 < \Phi \leq 0.25$</td><td colspan="2">2</td></tr><tr><td>$\Phi > 0.25$</td><td colspan="2">0</td></tr></table>	CTP Bondi ng bubble/ accidented spot	Size $\Phi(\text{mm})$	Acceptable Qty			A	B	$\Phi \leq 0.1$	Ignore		$0.15 < \Phi \leq 0.2$	3(distance $\geq 10\text{mm}$)		$0.2 < \Phi \leq 0.25$	2		$\Phi > 0.25$	0			
CTP Bondi ng bubble/ accidented spot	Size $\Phi(\text{mm})$		Acceptable Qty																			
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	$0.2 < \Phi \leq 0.25$		2																			
	$\Phi > 0.25$	0																				
	Assembly deflection	beyond the edge of backlight $\leq 0.2\text{mm}$																				
	<table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>$X \leq 0.5\text{mm}$</td><td>$Y \leq 0.5\text{mm}$</td><td>$Z < \text{cover t hickness}$</td></tr></table> TP cover broken X : length Y : width Z : height	X	Y	Z	$X \leq 0.5\text{mm}$	$Y \leq 0.5\text{mm}$	$Z < \text{cover t hickness}$	* Circuitry broken is not allowed.														
X	Y	Z																				
$X \leq 0.5\text{mm}$	$Y \leq 0.5\text{mm}$	$Z < \text{cover t hickness}$																				
	<table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>$X \leq 0.3\text{mm}$</td><td>$Y \leq 0.3\text{mm}$</td><td>$Z < \text{LCD thickness}$</td></tr></table> TP cover broken X : length Y : width Z : height	X	Y	Z	$X \leq 0.3\text{mm}$	$Y \leq 0.3\text{mm}$	$Z < \text{LCD thickness}$	* Circuitry broken is not allowe d.														
X	Y	Z																				
$X \leq 0.3\text{mm}$	$Y \leq 0.3\text{mm}$	$Z < \text{LCD thickness}$																				

Criteria (functional items)



Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	TP no function	Not allowed



12. Reliability Test Result

Item	Condition	Inspection after test
High Temperature Operating	85°C,96H	Inspection after 2~4hours storage at room temperature, the sample shall be free from defects: 1.Air bubble in the LCD; 2.Non-display; 3.Missing segments/line; 4.Glass crack; 5.Current IDD is twice higher than initial value.
Low Temperature Operating	-30°C, 96HR	
High Temperature Storage	85°C, 96HR	
Low Temperature Storage	-30°C, 96HR	
High Temperature & High Humidity Operating	+60°C, 90% RH ,96 hours.	
Thermal Shock (Non-operation)	-30°C,30 min ↔ 85°C,30 min, Change time:5min 20CYC.	
ESD test	C=150pF, R=330,5points/panel Air:±8KV, 5times; Contact:±6KV, 5 times; (Environment: 15°C~35°C, 30%~60%).	
Vibration (Non-operation)	Frequency range:10~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z. (6 hours for total) (Package condition).	
Box Drop Test	1 Corner 3 Edges 6 faces,80cm(MEDIUM BOX)	

Remark:

- 1.The test samples should be applied to only one test item.
- 2.Sample size for each test item is 5~10pcs.
- 3.For Damp Proof Test, Pure water(Resistance > 10MΩ) should be used.
- 4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.
- 5.Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.



13. Cautions and Handling Precautions

13.1 Handling and Operating the Module

(1) When the module is assembled, it should be attached to the system firmly.

Do not warp or twist the module during assembly work.

(2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.

(3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.

(4) Do not allow drops of water or chemicals to remain on the display surface.

If you have the droplets for a long time, staining and discoloration may occur.

(5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.

(6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.

Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.

(7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.

(8) Protect the module from static; it may cause damage to the CMOS ICs.

(9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.

(10) Do not disassemble the module.

(11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.

(12) Pins of I/F connector shall not be touched directly with bare hands.

(13) Do not connect, disconnect the module in the "Power ON" condition.

(14) Power supply should always be turned on/off by the item 6.1 Power On Sequence & 6.2 Power Off Sequence

13.2 Storage and Transportation.

(1) Do not leave the panel in high temperature, and high humidity for a long time.

It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%

(2) Do not store the TFT-LCD module in direct sunlight.

(3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.

(4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.

In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.

(5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.



14. Packing

---TBD-----

